

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
PATENT APPLICATION**

Appl. No.: 10/695,026	Confirmation No.: 5704
Applicant: Sunil Thomas	
Filed: October 28, 2003	
TC/AU: 2813	
Examiner: Jack S. J. Chen	
Docket: TI-29525.1A	
Cust. No.: 23494	
Title: Flip-Chip Assembly of Protected Micromechanical Devices	

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**Supplement to Previous Amendments under 37 CFR § 1.111**

Dear Sir:

In response to the non-final Office Action mailed September 21<sup>st</sup>, 2006 in connection with the above identified application, Applicant respectfully submits the following amendments and remarks:

**Amendments to the Claims** begin on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.